

POLYMER BLENDS BASED ON POLYAMIDE

ABSTRACT OF THE DISCLOSURE

A molding composition that features low water absorption, low thermal expansion and mold shrinkage is disclosed. The composition that optionally contains fillers or reinforcing agents contains polyamide, an impact modifier and a member selected from the group consisting of phenol-formaldehyde resin, an oligomeric or polymeric compound having at least 2 phenolic hydroxyl groups per molecule. Further optional components are compatibility promoter and a vinyl (co)polymer.